

DW PACKAGE

(TOP VIEW)

16

15

14

13

12

11

10

9

SHUTDOWN

🖵 GND

T AOUT

T SYNC

P0008-01

T RT

BOUT

10

2

3

4

5

6

7

8

CL SS 🗖

VREF 🗖

CS- 🗖

CS+ 🞞

EA+

EA-

СТ 🗖

COMP

FEATURES

- **Pin-for-Pin Compatible With the UC2846**
- 65-ns Typical Delay From Shutdown to Outputs and 50-ns Typical Delay From Sync to Outputs
- Improved Current Sense Amplifier With Reduced Noise Sensitivity
- **Differential Current Sense With 3-V Common Mode Range**
- Trimmed Oscillator Discharge Current for . Accurate Deadband Control
- Accurate 1-V Shutdown Threshold
- **High Current Dual Totem Pole Outputs (1.5-A peak)**
- **TTL Compatible Oscillator SYNC Pin** WWW.DZSC.COM Thresholds
- **4-kV ESD Protection**

DESCRIPTION

The UC2856 is a high performance version of the popular UC2846 series of current mode controllers, and is intended for both design upgrades and new applications where speed and accuracy are important. All input to output delays have been minimized, and the current sense output is slew rate limited to reduce noise sensitivity. Fast 1.5-A peak output stages have been added to allow rapid switching of power FETs.

A low impedance TTL compatible sync output has been implemented with a 3-state function when used as a sync input.

Internal chip grounding has been improved to minimize internal noise caused when driving large capacitive loads. This, in conjunction with the improved differential current sense amplifier, results in enhanced noise immunity.

Other features include a trimmed oscillator current (8%) for accurate frequency and dead time control; a 1 V, 5% shutdown threshold; and 4 kV minimum ESD protection on all pins.

ORDERING INFORMATION⁽¹⁾

T _A	PACKAGE		ORDERABLE PART NUMBER	TOP-SIDE MARKING	
–40°C to 125°C	SOP-DW	Tape and reel	UC2856QDWR	UC2856Q	

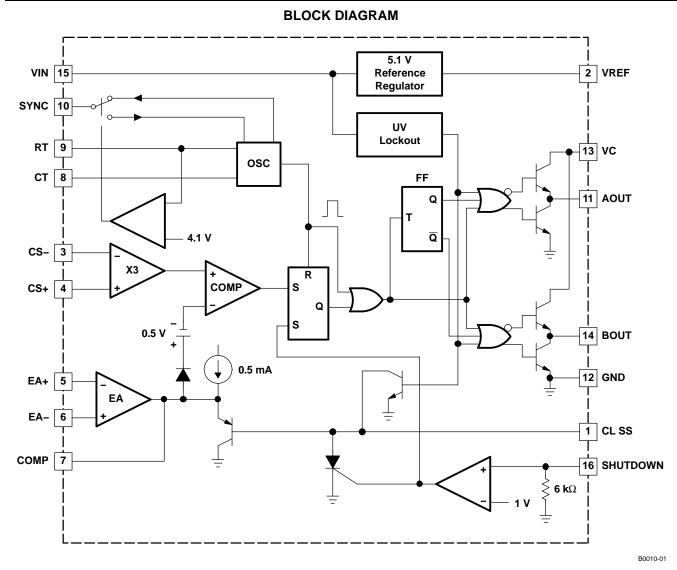
(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

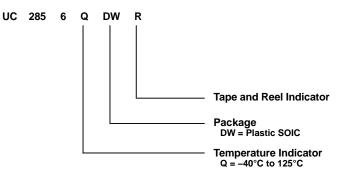
UC2856Q

SGLS265-NOVEMBER 2004





ORDERING INFORMATION





ABSOLUTE MAXIMUM RATINGS

over operating free-air temperature range (unless otherwise noted) $^{(1)(2)}$

			UNIT
	Supply voltage	40 V	
	Collector supply voltage	40 V	
		DC	0.5 A
I _O	Output current (sink or source)	Pulse (0.5 ms)	2 A
	Error amplifier input voltage		-0.3 V to VIN
	Shutdown input voltage	–0.3 V to 10 V	
	Current sense input voltage	-0.3 V to 3 V	
	SYNC output current	±10 mA	
	Error amplifier output current		-5 mA
	Soft start sink current		50 mA
	Oscillator charging current		5 mA
	Dewen dissipation	$T_A = 25^{\circ}C$	1 W
	Power dissipation	$T_{\rm C} = 25^{\circ}{\rm C}$	2 W
TJ	Operating junction temperature rar	–55°C to 150°C	
T _{stg}	Storage temperature range		–65°C to 150°C
-	Lead temperature soldering 1,6 m	300°C	

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) Unless otherwise indicated, voltages are reference to ground and currents are positive into and negative out of the specified terminals.

ELECTRICAL CHARACTERISTICS

 $T_A = -40^{\circ}C$ to 125°C, VIN = 15 V, RT = 10 k Ω , CT = 1 nF, and $T_A = T_J$ (unless otherwise stated)⁽¹⁾

PARAMETER	TEST C	ONDITIONS	MIN	TYP	MAX	UNIT
REFERENCE SECTION						
Output voltage	I _O = 1 mA,	$T_J = 25^{\circ}C$	5.05	5.1	5.15	V
Line regulation voltage	VIN = 8 V to 40 V				20	mV
Load regulation voltage	$I_0 = -1$ mA to -10 mA				15	mV
Total output variation	Line, Load, and Tempera	ature	5		5.2	V
Output noise voltage	f = 10 Hz to 10 kHz,	$T_J = 25^{\circ}C$		50		μV
Long term stability	1000 hours, ⁽²⁾	$T_J = 25^{\circ}C$		5	25	mV
Short circuit current	VREF = 0 V		-25	-45	-65	mA
OSCILLATOR SECTION						
	$T_J = 25^{\circ}C$		180	200	220	
Initial accuracy	T _J = Full range	170		230	kHz	
Voltage stability	VIN = 8 V to 40 V				2%	
Discharge ourrent	VCT = 2 V,	$T_J = 25^{\circ}C$	7.5	8	8.8	mA
Discharge current	VCT = 2 V	6.7	8	8.8	mA	
Sync output high level voltage	$I_0 = -1 \text{ mA}$		2.4	3.6		V
Sync output low level voltage	I _O = 1 mA			0.2	0.4	V
Sync input high level voltage	CT = 0 V, RT = VREF		2	1.5		V
Sync input low level voltage	CT = 0 V, RT = VREF			1.5	0.8	V
Sync input current	CT = 0 V, RT = VREF,V	_{SYNC} = 5 V		1	10	μA
Sync delay to outputs	CT = 0 V RT = VREF, V _{SYNC} = 0.8 V to 2 V				100	ns

(1) All voltages are with respect to GND. Currents are positive into, negative out of the specified terminal.

(2) This parameter, although specified over the recommended operating conditions, is not 100% tested in production.

SGLS265-NOVEMBER 2004



ELECTRICAL CHARACTERISTICS (continued)

$T_A = -40^{\circ}C$ to 125°C, VIN = 15 V, RT = 10 k Ω , CT = 1 nF, and $T_A = T_J$ (unless otherwise stated)

PARAMETER	TEST CO	NDITIONS	MIN	TYP	MAX	UNIT
ERROR AMPLIFIER SECTION						
Input offset voltage	$V_{CM} = 2 V$				5	mV
Input bias current					-1	μA
Input offset current					500	nA
Common mode range	VIN = 8 V to 40 V		0		VIN–2	V
Open loop gain	$V_0 = 1.2 \text{ V to } 3 \text{ V}$		80	100		dB
Unity gain bandwidth	$T_J = 25^{\circ}C$		1	1.5		MHz
CMRR	$V_{CM} = 0 V \text{ to } 38 V,$	VIN = 40 V	75	100		dB
PSRR	VIN = 8 V to 40 V		80	100		dB
Output sink current	V _{ID} = -15 mV	V _{COMP} = 1.2 V	5	10		mA
Output source current	V _{ID} = 15 mV	$V_{COMP} = 2.5 V$	-0.4	-0.5		mA
High-level output voltage	V _{ID} = 50 mV,	R_L (COMP) = 15 k Ω	4.3	4.6	4.9	V
Low-level output voltage	V _{ID} = -50 mV,	R_L (COMP) = 15 k Ω		0.7	1	V
CURRENT SENSE AMPLIFIER SECTION	1					
Amplifier gain	$V_{CS-} = 0 V,$	CL SS Open ⁽³⁾⁽⁴⁾	2.5	2.75	3	V/V
Maximum differential input signal (V _{CS+} - V _{CS-})	CL SS Open 3,	R_L (COMP) = 15 k Ω	1.1	1.2		V
Input offset voltage	V _{CL SS} = 0.5 V	COMP open ⁽⁵⁾		5	35	mV
CMRR	$V_{CM} = 0 V \text{ to } 3 V$		60			dB
PSRR	VIN = 8 V to 40 V		60			dB
Input bias current	V _{CL SS} = 0.5 V,	COMP open ⁽⁵⁾			-1	μA
Input offset current	V _{CL SS} = 0.5 V,	COMP open ⁽⁵⁾			1	mA
Input common mode range			0		3	V
Delay to outputs	$V_{EA+} = VREF, EA- = 0 V,$	CS+ – CS– = 0 V to 1.5 V		120	250	ns
CURRENT LIMIT ADJUST SECTION		·				
Current limit offset	$V_{CS-} = 0 V, V_{CS+} = 0 V,$	COMP Open ⁽⁵⁾	0.4	0.5	0.6	V
Input bias current	V _{EA+} = VREF,	V _{EA-} = 0 V		-10	-30	μA
SHUTDOWN TERMINAL SECTION						
Threshold voltage			0.95	1.00	1.05	V
Input voltage range			0		5	V
Minimum latching current (I _{CL SS})			(6)3	1.5		mA
Maximum non-latching current (I _{CL SS})				⁽⁷⁾ 1.5	0.8	mA
Delay to outputs	V _{SHUTDOWN} = 0 V to 1.3 V			65	110	ns
OUTPUT SECTION						
Collector-emitter voltage			40			V
Off-state bias current	VC = 40 V				250	μA
	I _{OUT} = 20 mA			0.1	0.5	\ <i>\</i>
Output low level voltage	I _{OUT} = 200 mA		0.5	2.6	V	
Output high lovel veltage	$I_{OUT} = -20 \text{ mA}$			13.2		14
Output high level voltage	I _{OUT} = -200 mA	12	13.1		V	
Rise time	C1 = 1 nF			40	80	ns
Fall time	C1 = 1 nF			40	80	ns

(3) Parameter measured at trip point of latch with VEA+ = VREF, VEA- = 0 V.

$$C = {}^{\Delta V} COMP.$$

$$G = \frac{\Delta^{V} COMP}{\Delta V_{CS} +}; \ \Delta V_{CS} - = 0 \ V \ 1 \ V.$$

Amplifier gain defined as (4) (5) Parameter measured at trip point of latch with VEA+ = VREF, VEA- = 0 V.

(6) Current into CL SS assured to latch circuit into shutdown state.

(7) Current into CL SS assured not to latch circuit into shutdown state.

ELECTRICAL CHARACTERISTICS (continued)

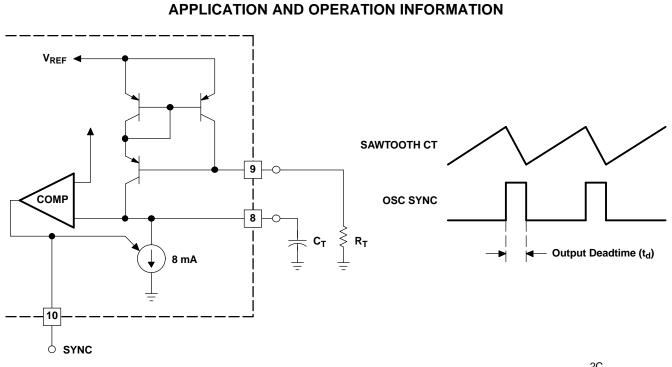
$T_A = -40^{\circ}C$ to 125°C, VIN = 15 V, RT = 10 k Ω , CT = 1 nF, and $T_A = T_J$ (unless otherwise stated)

PARAMETER	TES	MIN	TYP	MAX	UNIT	
UVLO low saturation	VIN = 0 V,		0.8	1.5	V	
PWM SECTION						
Maximum duty cycle			45%	47%	50%	
Minimum duty cycle					0%	
UNDERVOLTAGE LOCKOUT SECTION						
Startup threshold				7.7	8	
Threshold hysterisis				0.7		
TOTAL STANDBY CURRENT						
Supply current				18	23	mA



SGLS265-NOVEMBER 2004





NOTE: Output deadtime is determined by the size of the external capacitor, C_{T} , according to the formula: For large values of R_T : Td = 250 C_T $f_{\mathsf{T}} = \frac{2}{\mathsf{R}_{\mathsf{T}} \times \mathsf{C}_{\mathsf{T}}}$ Oscillator frequency is approximated by the formula:



V_{IN} = 20 V

T_J = 25°

S0019-01

Open-Loop Phase – 6

G001

0

10M

-90

-180

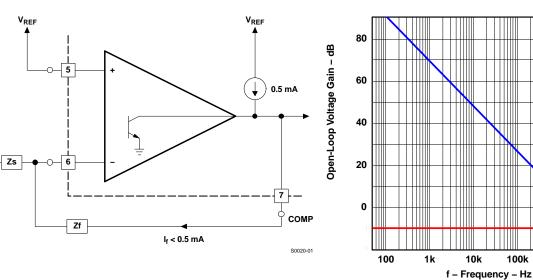


Figure 1. Oscillator Circuit

Figure 3. Error Amplifier Gain and Phase vs Frequency

100k

1M

NOTE: Error Amplifier can source up to 0.5 mA. Figure 2. Error Amplifier Output Configuration



APPLICATION AND OPERATION INFORMATION (continued)

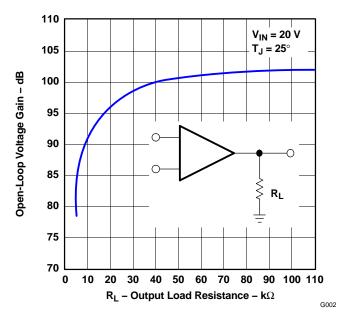
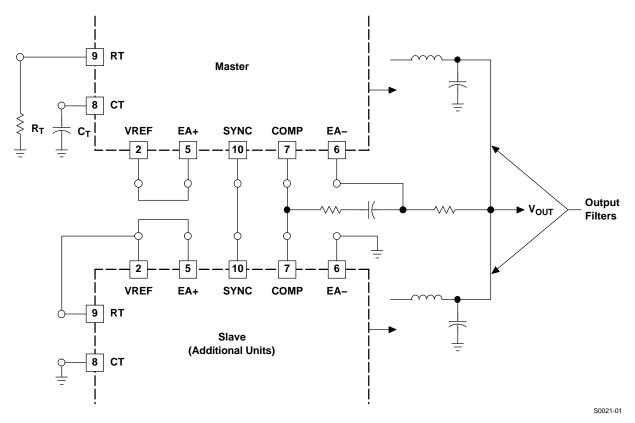


Figure 4. Error Amplifier Open-Loop DC Gain vs Load Resistance



NOTE: Slaving allows parallel operation of two or more units with equal current sharing.

Figure 5. Parallel Operation

UC2856Q

SGLS265-NOVEMBER 2004



APPLICATION AND OPERATION INFORMATION (continued)

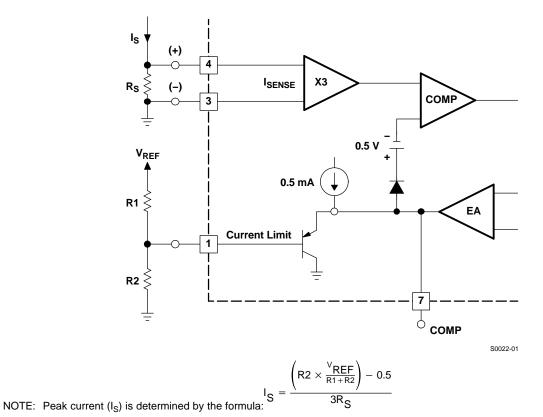
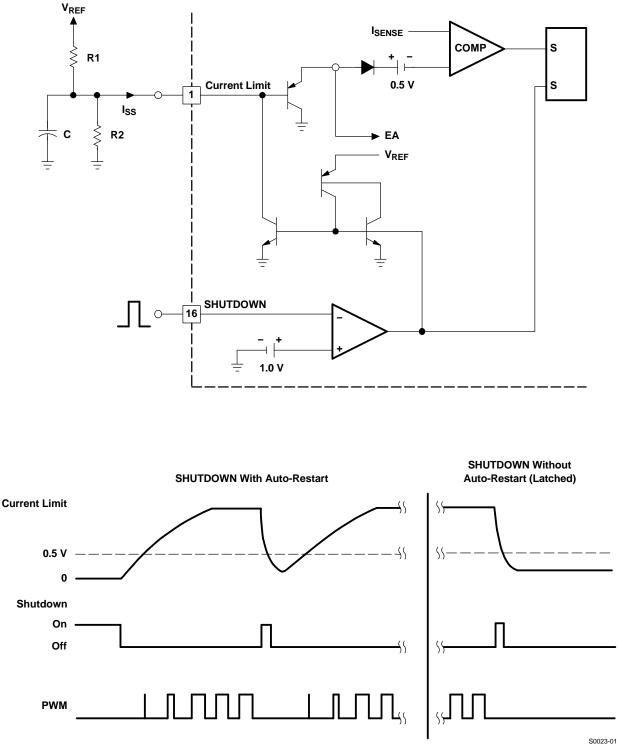


Figure 6. Pulse by Pulse Current Limiting



APPLICATION AND OPERATION INFORMATION (continued)



NOTE: If V_{REF} / R1 < 0.8 mA, the shutdown latch commutates when I_{SS} = 0.8 mA and a restart cycle will be initiated. If V_{REF} / R1 > 3 mA, the device will latch off until power is recycled.

Figure 7. Shutdown

27-Feb-2006

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins Pa	ackage Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
UC2856QDWR	ACTIVE	SOIC	DW	16	2000	TBD	CU SNPB	Level-2-220C-1 YEAR

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

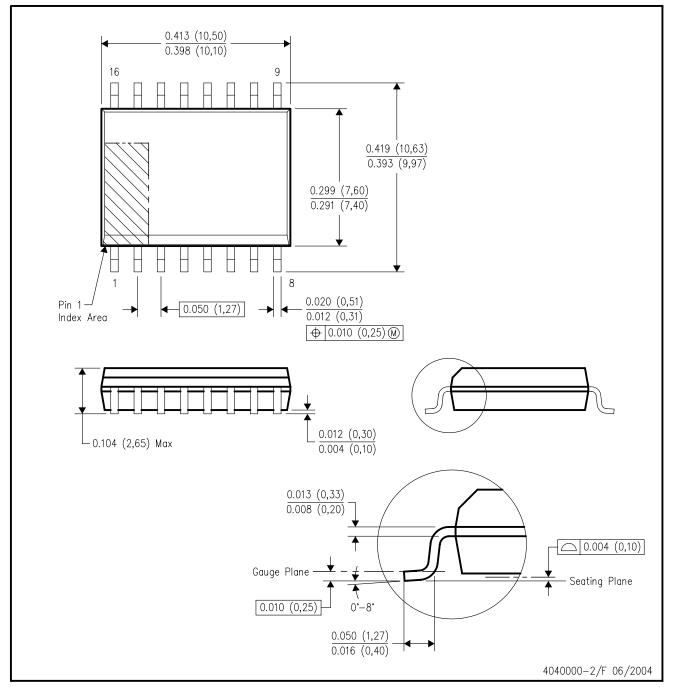
⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer:The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

DW (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-013 variation AA.



IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products		Applications	
Amplifiers	amplifier.ti.com	Audio	www.ti.com/audio
Data Converters	dataconverter.ti.com	Automotive	www.ti.com/automotive
DSP	dsp.ti.com	Broadband	www.ti.com/broadband
Interface	interface.ti.com	Digital Control	www.ti.com/digitalcontrol
Logic	logic.ti.com	Military	www.ti.com/military
Power Mgmt	power.ti.com	Optical Networking	www.ti.com/opticalnetwork
Microcontrollers	microcontroller.ti.com	Security	www.ti.com/security
		Telephony	www.ti.com/telephony
		Video & Imaging	www.ti.com/video
		Wireless	www.ti.com/wireless

Mailing Address: Texas Instruments

Post Office Box 655303 Dallas, Texas 75265